

Pelnox[®]

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| Product Name | ZC-206 |
| Product Category | Resin for Semiconduntors, One Component Type Resin |
| Usage | Semiconductor Modules, General Modules |
| Function | One Component Type, Low Stress, Low Shrinkage, Low Warpage, Heat Cycle Resistant |

As supplied

(Typical Value)

| Item | Condition | Unit | ZC-206 |
|------------------|-----------|-------|-------------|
| Appearance | visual | – | Black paste |
| Specific Gravity | 25°C | – | 2.00 |
| Viscosity | 25°C | mPa·s | 82,000 |

Standard Curing Condition 150°C x 1 hour + 150°C x 1hour

As cured

| Item | Condition | Unit | Typical Value |
|----------------------------------|--------------------------|----------------------|-------------------|
| Hardness | JIS K-7215 25°C | Shore D | 97 |
| Heat Distortion Temperature | TMA | °C | 146 |
| Coefficient of Thermal Expansion | below Tg | 10 ⁻⁵ /°C | 9.9 |
| | above Tg | 10 ⁻⁵ /°C | 4.2 |
| Flexural Strength | JIS K-6911 | MPa | 180 |
| Flexural Modulus | JIS K-6911 | MPa | 18,000 |
| Volume Resistivity | JIS K 6911 25°C | Ω-cm | >10 ¹⁶ |
| Water Absorption | JIS K 6911 boil for 2hrs | wt% | 0.04 |
| | 85°C85% for 168hrs | wt% | 0.25 |
| | PCT(121°C-100%) 100hrs | wt% | 0.52 |

The above values are typical and not specification.



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